



Product Change Notification: BLAS-14JRLN114

Date:

22-Jun-2026

Product Category:

Gate Drivers and Motor Drivers, Linear Regulators, Power Management - PMIC, Power Management - Power Switches, Power Management - PWM Controllers

Notification Subject:

CCB 8308 Initial Notice: Qualification of MMT as an additional assembly site for MIC2101YML-TR, MIC2102YML-TR, MIC2103YML-TR, MIC2104YML-TR, MIC2550AYML-TR, MIC2550YML-TR, MIC4555YML-TR, MIC4600YML-T5, MIC4600YML-TR, MIC4742YML-TR, MIC4744YML-TR, MIC4782YML-TR and SPN030050G-TR catalog part numbers (CPN) available in 16L VQFN (3x3x1.00mm) package.

Affected CPNs:

[BLAS-14JRLN114_Affected_CPN_06222026.pdf](#)

[BLAS-14JRLN114_Affected_CPN_06222026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for MIC2101YML-TR, MIC2102YML-TR, MIC2103YML-TR, MIC2104YML-TR, MIC2550AYML-TR, MIC2550YML-TR, MIC4555YML-TR, MIC4600YML-T5, MIC4600YML-TR, MIC4742YML-TR, MIC4744YML-TR, MIC4782YML-TR and SPN030050G-TR catalog part numbers (CPN) available in 16L VQFN (3x3x1.00mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Unisem (M) Berhad Perak, Malaysia (UNIS)	Unisem Gopeng (UNIG)	Unisem (M) Berhad Perak, Malaysia (UNIS)	Unisem Gopeng (UNIG)	Microchip Technology Thailand (Branch) (MMT)	Yes
MSL	MSL-2	MSL-2	MSL-2	MSL-2	MSL-1	Yes
Wire Material	Au	Au	Au	Au	CuPdAu	Yes
Die Attach Material	8290 (PFAS)	8290 (PFAS)	8290 (PFAS)	8290 (PFAS)	QMI519 (PFAS-free)	Yes
Molding Compound Material	G770HC D	G770HC D	G770HC D	G770HC D	G700LTD	Yes
Lead-Frame Material	A194	A194	A194	A194	A194	No
Lead-Frame Paddle Size	69x69 mils	69x69 mils	69x69 mils	69x69 mils	75x75 mils	Yes
Lead-Frame Lead-lock	Yes (Dimple)	Yes (Dimple)	Yes (Dimple)	Yes (Dimple)	Yes (Locking Hole)	Yes
Lead-Frame Design	See Pre and Post Change for Comparison.					

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery and manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: August 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	August 2026				
Work Week	23	24	25	26	27		31	32	33	34	35
Initial PCN Issue Date				X							
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: June 22, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-14JRLN114_Pre_and_Post_Change Summary.pdf
PFAS Elimination and Die Attach_Explanation.pdf
PCN_BLAS-14JRLN114 Qualification Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MIC4600YML-TR

MIC4742YML-TR

MIC4744YML-TR

MIC4782YML-TR

SPN030050G-TR

MIC2101YML-TR

MIC2102YML-TR

MIC2103YML-TR

MIC2104YML-TR

MIC2550AYML-TR

MIC2550YML-TR

MIC4555YML-TR

MIC4600YML-T5



QUALIFICATION PLAN SUMMARY

PCN #: BLAS-14JRLN114

**Date:
Jun 04, 2026**

**Qualification of MMT as an additional assembly site for
MIC2101YML-TR, MIC2102YML-TR, MIC2103YML-TR, MIC2104YML-
TR, MIC2550AYML-TR, MIC2550YML-TR, MIC4555YML-TR,
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TR, MIC4782YML-TR and SPN030050G-TR catalog part numbers
(CPN) available in 16L VQFN (3x3x1.00mm) package.**

Purpose: Qualification of MMT as an additional assembly site for MIC2101YML-TR, MIC2102YML-TR, MIC2103YML-TR, MIC2104YML-TR, MIC2550AYML-TR, MIC2550YML-TR, MIC4555YML-TR, MIC4600YML-T5, MIC4600YML-TR, MIC4742YML-TR, MIC4744YML-TR, MIC4782YML-TR and SPN030050G-TR catalog part numbers (CPN) available in 16L VQFN (3x3x1.00mm) package.

CCB #: 8308

Misc.	Assembly site	MMT
	BD Number	BDM-003002/01
	MP Code (MPC)	29601YNCAA01
	Part Number (CPN)	MIC2101YML-TR
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	100
	Reliability Site	MTAI
Lead-Frame	Paddle size	75x75 mils
	Material	A194
	DAP Surface Prep	NIPdAu-PPF
	Treatment	Roughened
	Process	Etched
	Lead-lock	Yes (Locking Hole)
	Part Number	10101615
	Lead Plating	NIPdAu-PPF
	Strip Size	250x70mm
	Strip Density	1179 units/strip
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519 (PFAS-free)
	Conductive	Yes
MC	Part Number	G700LTD
PKG	Package Type	VQFN
	Pin/Ball Count	16
	PKG width/size	3x3x1.0mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5		MMT/MTAI	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5		MMT/MTAI	30 bonds from a min. 5 devices.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5		MMT/MTAI	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours Electrical test pre and post stress at +25°C and +125°C hot temp.	45	5	3	150	0	10	MTAI	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-1/260C	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C and +125°C hot temp.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at +125°C hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

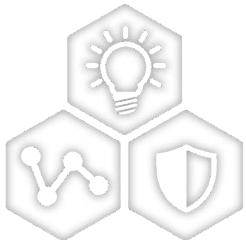
CCB 8308

Pre and Post Change Summary

PCN #: BLAS-14JRLN114

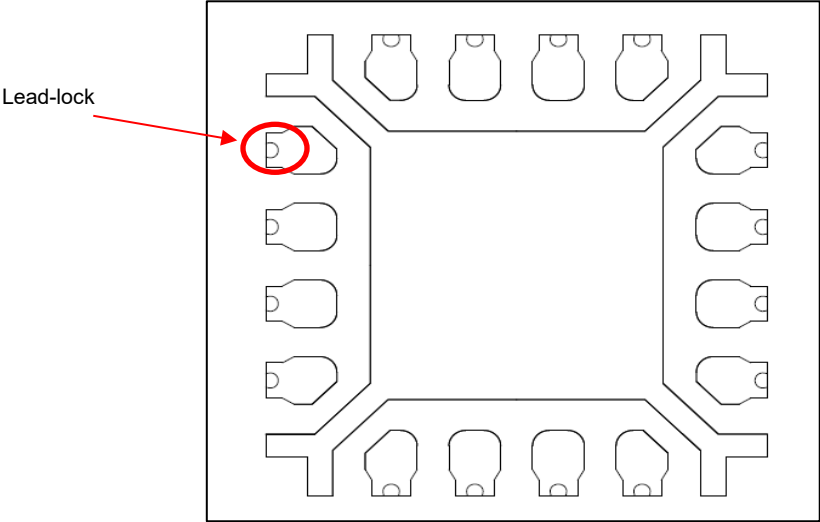
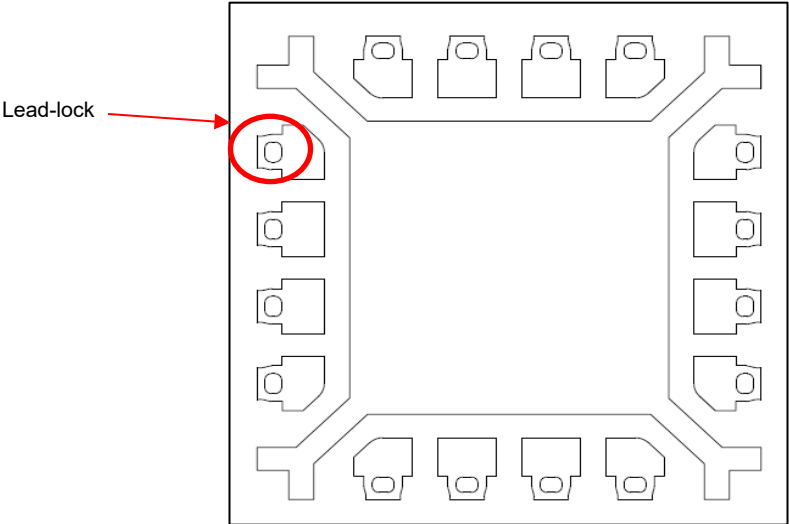


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Lead Frame Comparison

UNIS/UNIG	MMT												
 <table> <tr> <td>Lead-Frame Material</td><td>A194</td></tr> <tr> <td>Lead-lock Design</td><td>Dimple</td></tr> <tr> <td>Lead-frame Paddle Size</td><td>69x69 mils</td></tr> </table>	Lead-Frame Material	A194	Lead-lock Design	Dimple	Lead-frame Paddle Size	69x69 mils	 <table> <tr> <td>Lead-Frame Material</td><td>A194</td></tr> <tr> <td>Lead-lock Design</td><td>Locking Hole</td></tr> <tr> <td>Lead-frame Paddle Size</td><td>75x75 mils</td></tr> </table>	Lead-Frame Material	A194	Lead-lock Design	Locking Hole	Lead-frame Paddle Size	75x75 mils
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Lead-lock Design	Locking Hole												
Lead-frame Paddle Size	75x75 mils												

Note 1: Mold compound materials fills the leadlock hole, which provides improved protection against moisture penetration along the edge of leads (pins) of the package.

Note 2: Not to scale

Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Microchip
August 2025

Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

What is PFAS: Poly(Per) FluoroAlkyl Substances (PFAS)

Poly(Per) FluoroAlkyl Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
 - PFAS can be in the product itself.
 - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

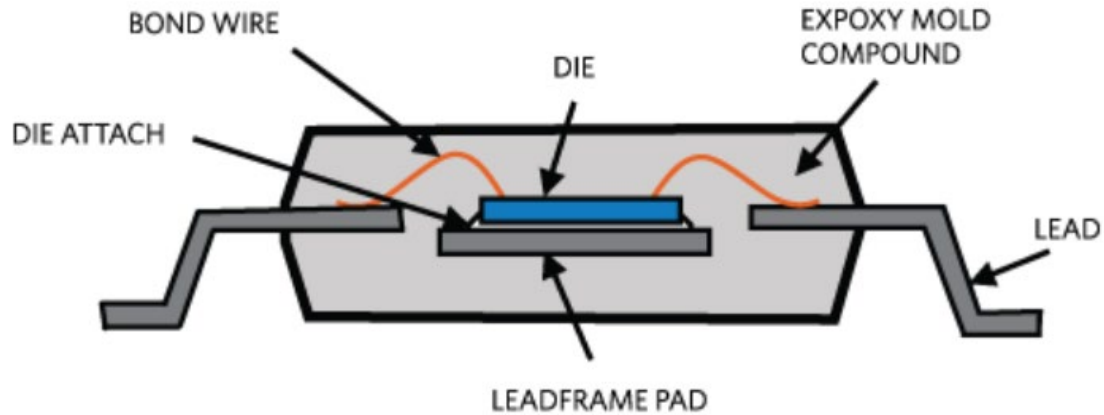
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

